

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): S. Tsuchikawa, et al.
Application No.: TBD
Filed: October 31, 2003
For: THERMOSETTING RESIN COMPOSITION AND USE THEREOF
Expected
Group: 1712
Expected
Examiner: D. Aylward

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 31, 2003

Sir:

Please amend the above-identified application, prior to examination thereof,
as listed in the following, and as set forth on the following pages:

Amendments to the Specification; and

Remarks are included following the amendments.